

The order is still given priority, and the fungal genus *Neolentinus* still contains all non-teleomorph species, e.g. *Neolentinus lepiodes* but also teleomorphs, e.g. *Neolentinus seriola*. Sections: Print [edit] Historical classification See also For an overview of the classification of fungal species over the years and a discussion of the nomenclature issues that led to the creation of the Index Fungorum. Following the discovery of the natural synamorph form of *Mucor* which was described in 1880 by W.H. Blackwell and based on the field observations of Charles Pegler, the name *Mucor* was taken over by Adolf Hildrik, who started the Index Fungorum. Since then, the Mucorales are now considered to be a subclass of the Zygomycetes which are in turn a subclass of the Ascomycetes. discovery A frame of wood or light alloy, usually six feet high and two feet wide. It is often used for the purpose of containment, or as a support for growing vegetables. It is called a 'greenhouse' when it is used for the indoor production of vegetables. If the frame is solid it must be supported on legs. A greenhouse frame is called a 'stick house' if it consists of a series of rafters which are arranged vertically and usually have a panel of glass or clear plastic facing on one side of them. The rafters and sides are usually arranged in a rectangle, where the east and west sides, which are usually the opposite side of the glass, is known as a 'wall'. A greenhouse frame that uses metal posts is known as a 'pier-and-beam' system. A traditional system of building a greenhouse is to use a frame of similar timber, usually redwood, and glass. This method is now being used very rarely. 1. Field of the Invention This invention relates to a semiconductor device. 2. Description of the Related Art A semiconductor device having a semiconductor chip mounted on a flip-chip type mounting substrate has been widely used. In such a semiconductor device, for example, aluminum (Al) or silver (Ag) bumps are formed on electrodes of the semiconductor chip, the Al or Ag bumps are pressed against conductive pads of the

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